

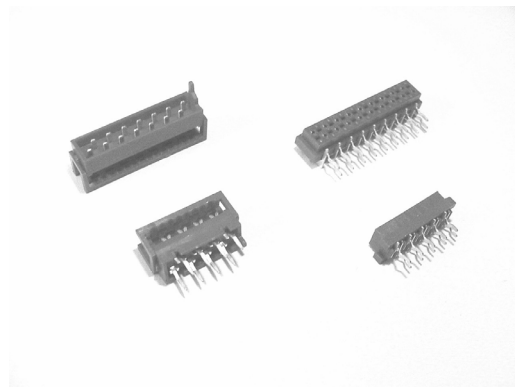
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Miniatur Steckverbinder - RM 2,54 mm

Miniature Connector - Pitch 2,54 mm

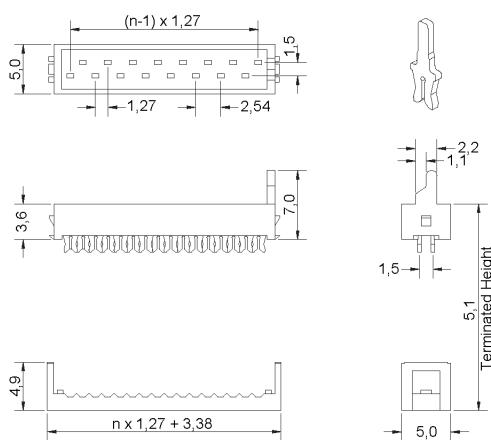
Technische Daten / Technical Data:

Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	Thermoplastic, rated UL94V0
Kontaktmaterial	Phosphorbronze, verzinkt
Contact Material	Phosphor Bronze, tin plated
Lötbarkeit	IEC512-12A
Solderability	IEC512-12A
Durchgangswiderstand	≤ 20 mOhm
Contact Resistance	≤ 20 mOhm
Isolationswiderstand	$> 3 \times 10^9$ Ohm
Insulation Resistance	$> 3 \times 10^9$ Ohm
Nennspannung	500 V _{AC}
Current Voltage	500 V _{AC}
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40°C...+105°C
Temperature Range	-40°C...+105°C
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	Reflow-Soldering, further informations in chapter T

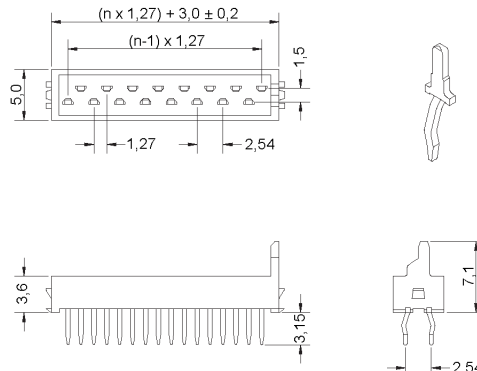


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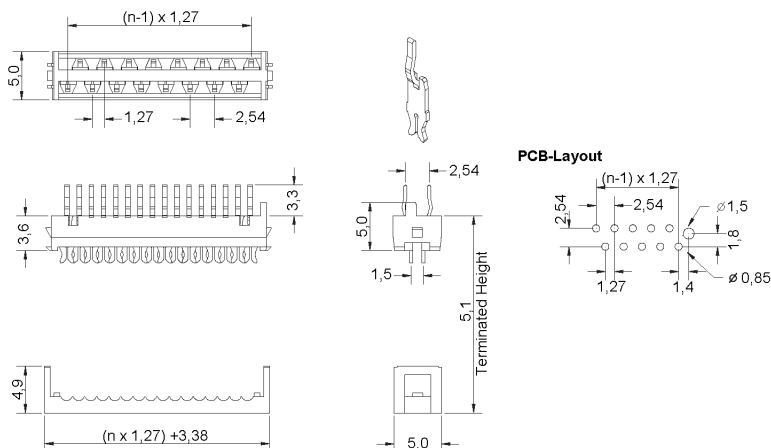
Male-on-Wire Connector



Male-on-Board Connector

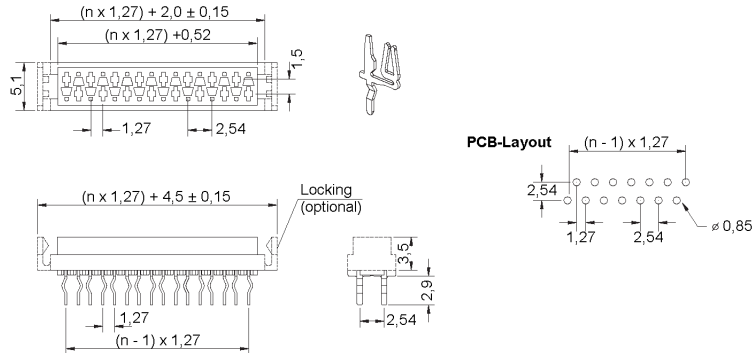


Paddle Board Connector

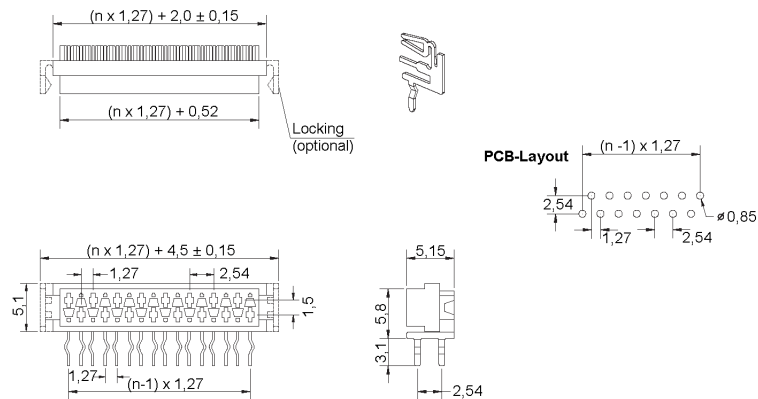


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Female-on-Board / Straight



Female-on-Board Connector / Right Angled



Series	Type*	Contacts*	Locking (Optional)*
699	1	20	
	1 = Stift zu Kabel Verbinder <i>Male-on-Wire Connector</i> 7 = Stift gerade <i>Male-on-Board Connector, Straight</i> 2 = Leiterplattenverbinder <i>Paddle Board Connector</i> 3 = Buchse, gerade <i>Female-on-Board Connector, Straight</i> 4 = Buchse, gewinkelt <i>Female-on-Board Connector, Right Angled</i>	04/06/08/10/12/ 14/16/18/20-pol.	0 = ohne Rastclip <i>w/o Locking</i> 1 = mit Rastclip <i>with Locking</i> (nur für Buchse verfügbar) (only available for Female Connectors)

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
 * Order example - To be replaced by your specifications.)

Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Lötten
Durchschnitts-Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / Sek. Max.
Vorheizen - Temperatur Min ($T_{s_{min}}$) - Temperatur Max ($T_{s_{max}}$) - Zeit ($t_{s_{min}}$ auf $t_{s_{max}}$)	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (T_p)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (t_p)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

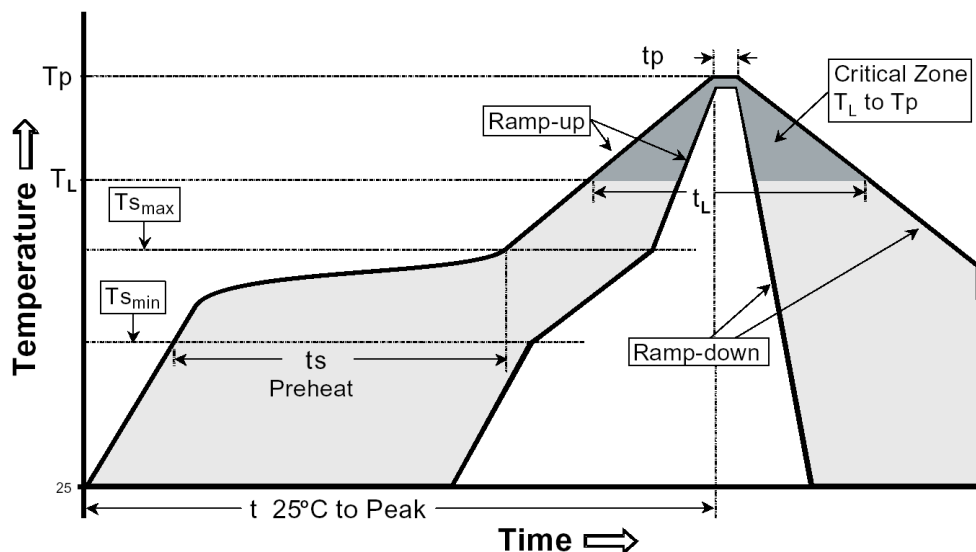
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Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / second max.
Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Max ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$)	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

Recommended Reflow-Soldering profile:



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